

REVERSE VOLTAGE: 50 to 1000 VOLTS

FORWARD CURRENT: 10.0 AMPERE

FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low forward voltage drop
- Low reverse leakage current
- High surge current capability

MECHANICAL DATA

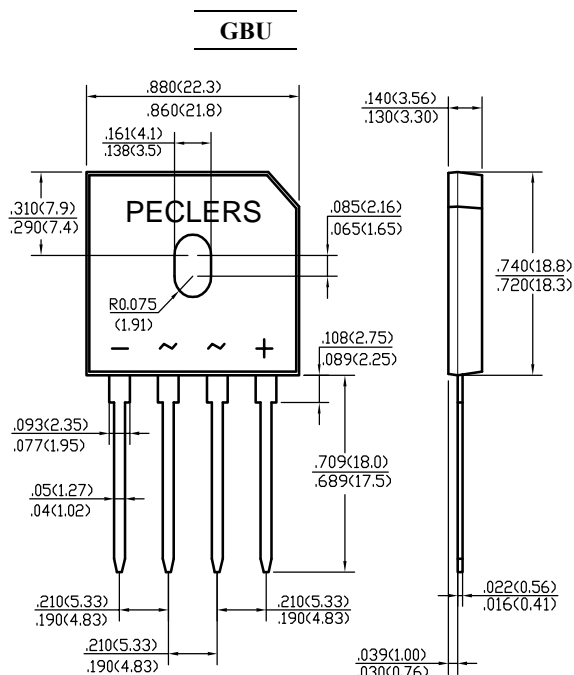
Case: Molded plastic, GBU

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed

Mounting position: Any

Weight: 0.15ounce, 4.0gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

| | Symbols | GBU10005 | GBU1001 | GBU1002 | GBU1004 | GBU1006 | GBU1008 | GBU1010 | Units |
|--|-----------------|-------------|---------|---------|---------|---------|---------|---------|-------|
| Maximum Recurrent Peak Reverse Voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum RMS Voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | Volts |
| Maximum DC Blocking Voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum Average Forward Rectified Current at $T_C=100^\circ\text{C}$ | $I_{(AV)}$ | 10.0 | | | | | | | Amp |
| Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method) | I_{FSM} | 200 | | | | | | | Amp |
| Maximum Forward Voltage at 5.0A DC and 25 °C | V_F | 1.0 | | | | | | | Volts |
| Maximum Reverse Current at $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage $T_A=125^\circ\text{C}$ | I_R | 5.0 500 | | | | | | | uAmp |
| Typical Junction Capacitance (Note 3) | C_J | 255 | | | | 125 | | | pF |
| Typical Thermal Resistance (Note 1) | $R_{\theta JA}$ | 8.6 | | | | | | | °C/W |
| Typical Thermal Resistance (Note 2) | $R_{\theta JC}$ | 3.1 | | | | | | | °C/W |
| Operating and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | | | | | | | °C |

NOTES:

- 1- Units Mounted in free air, no heatsink, P.C.B at 0.375" (9.5mm) lead length with 0.5 x 0.5" (12 x 12mm) copper pads.
- 2- Units Mounted on a 2.6 x 1.4" x 0.06" thick (6.5 x 3.5 x 0.15cm) AL plate.
- 3- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
- 4- Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screws

RATINGS AND CHARACTERISTIC CURVES

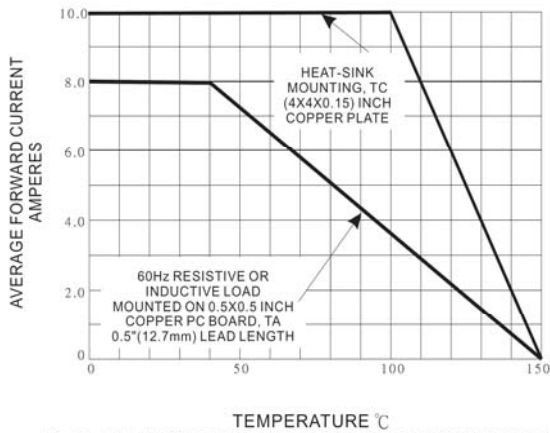


Fig. 1 - DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

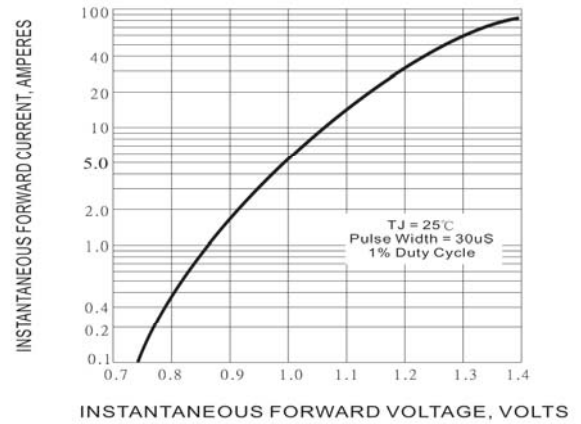


Fig. 2 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER ELEMENT

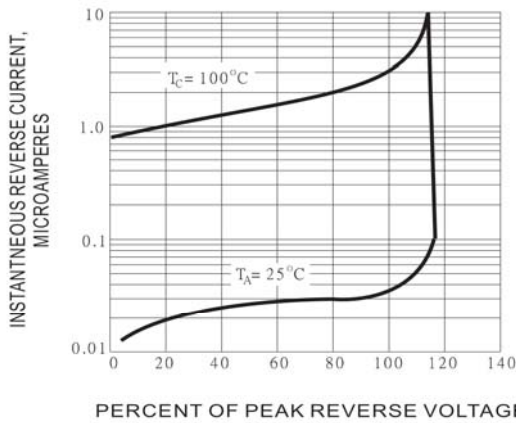


Fig. 3 - TYPICAL REVERSE CHARACTERISTICS

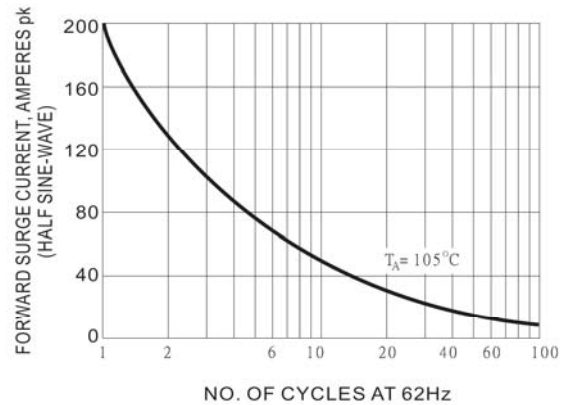


Fig. 4 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

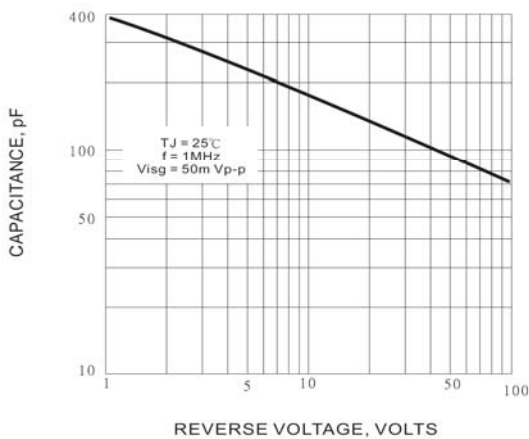


Fig. 5 - TYPICAL JUNCTION CAPACITANCE PER ELEMENT